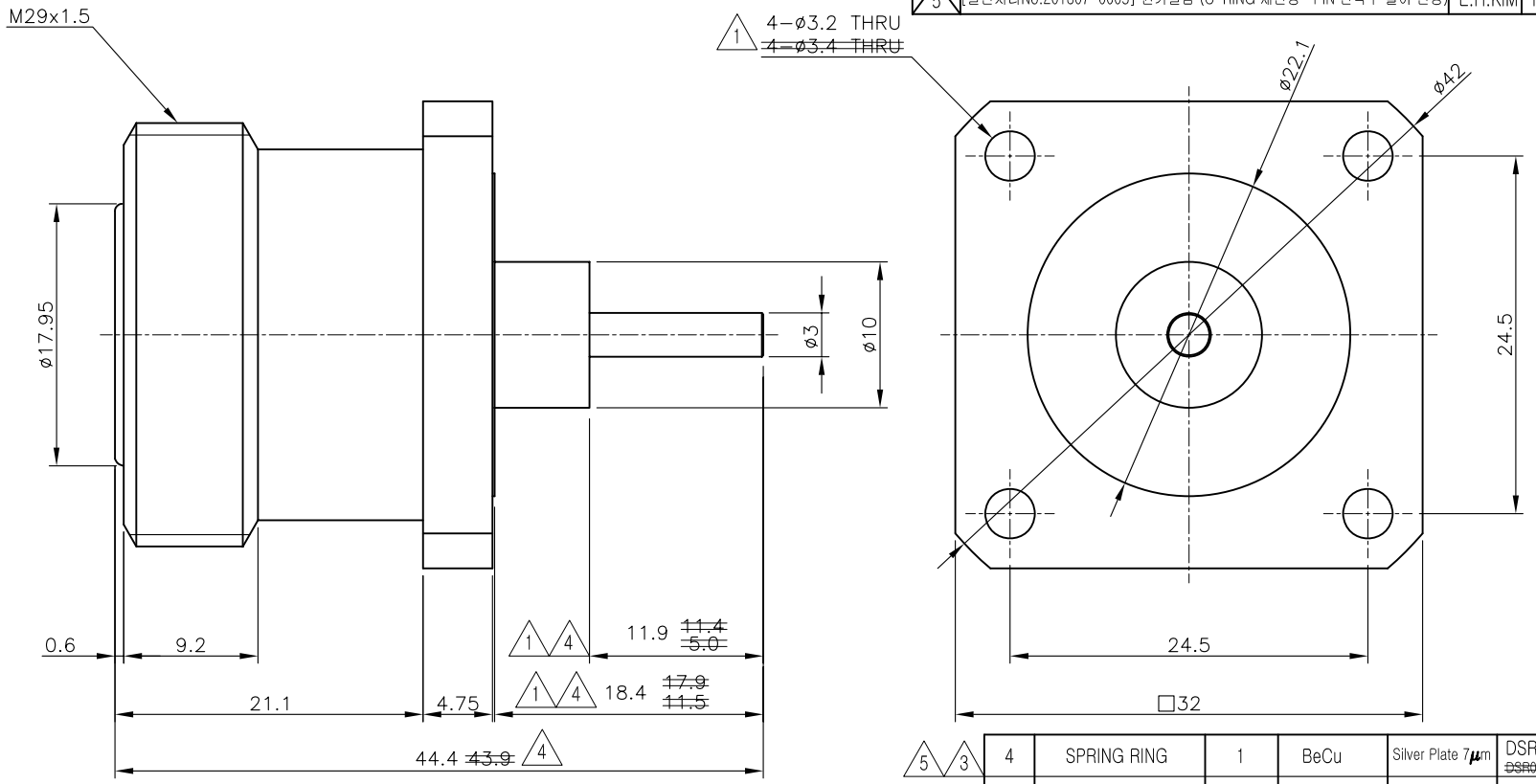
REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	Y.H.CHOI	2010.07.13.
1	[설변No. 201101-0003] 업체요청. 솔더부위 길이 및 장착 홀 사이즈 변경.	D.W.KANG	Y.H.CHOI	2011.01.25.
2	[설변No. 201103-0003] PIN 회전 방지 구조 및 치수 설변	I.C.KIM	Y.H.CHOI	2011.03.04.
3	[설변처리No.201104-0002] C-RING 및 PIN 안착부 길이 변경	I.C.KIM	Y.H.CHOI	2011.04.18.
4	[설변처리No.201109-0003] PIN 길이 설변 (SOLDER부 길이 0.5mm길게-파이럼 요청)	I.C.KIM	J.H.YOUN	2011.09.07.
5	[설변처리No.201307-0005] 원가절감 (C-RING 재변경- PIN 안착부 길이 변경)	E.H.KIM	I.C.KIM	2013.07.12.



	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
5 3	4	SPRING RING	1	BeCu	Silver Plate 7μm	DSR01054-5/2 ~~DSR01054-5/2~~ ~~DSR01056-5/1~~
	3	INSULATOR	1	TEFLON		DIN01817-N/1
5 4 3 2 1	2	CONTACT	1	MBsBD	Silver Plate 7μm	DCT02409-5/1 ~~DCT02388-5/1~~
2 1	1	BODY	1	MBsBD	SUCO Plate (3μm)	DBD02885-5/1 ~~DBD02799-5/1~~

TOLERANCE	Decimal ±0.2	DATE	2013. 07. 12.
	Angle ±1°	APPROVED BY	I.C.KIM
		CHECKED BY	
MATERIAL	-	DRAWN BY	E.H.KIM
FINISH	-	SCALE 2/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE
7/16 DIN50 SOLDER END JS-4H

A4 DWG NO. CN02588-7/2
REVISION 5 SHEET 1 of 1

주 기

1. □32 4면 엔드밀 작업시 적용 치수 (□32~□31.6)